

MA2Z360J (MA360J)

Silicon epitaxial planar type

For UHF and VHF electronic tuners

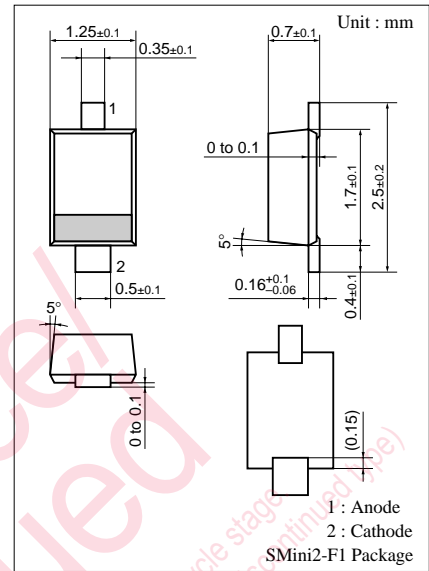
■ Features

- Large capacitance ratio
- Small series resistance r_D

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage (DC)	V_R	30	V
Peak reverse voltage*	V_{RM}	35	V
Forward current (DC)	I_F	20	mA
Junction temperature	T_j	150	$^\circ\text{C}$
Storage temperature	T_{stg}	-55 to +150	$^\circ\text{C}$

Note) * : $R_L = 10\text{ k}\Omega$



Marking Symbol: 6A

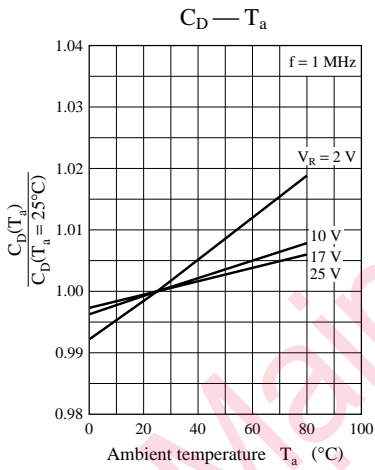
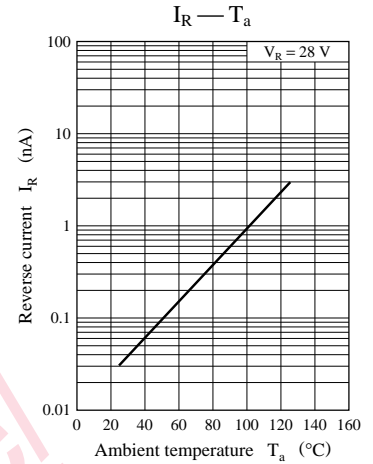
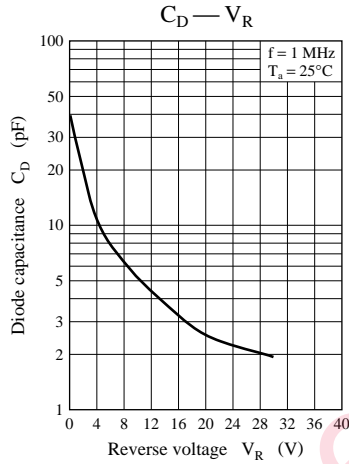
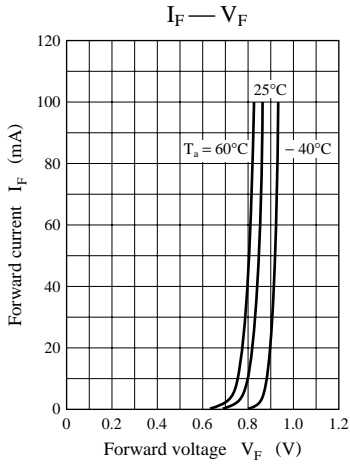
■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse current (DC)	I_R	$V_R = 28\text{ V}$			10	nA
Diode capacitance	$C_{D(2V)}$	$V_R = 2\text{ V}, f = 1\text{ MHz}$	14.360		16.340	pF
	$C_{D(25V)}$	$V_R = 25\text{ V}, f = 1\text{ MHz}$	2.089		2.448	pF
	$C_{D(10V)}$	$V_R = 10\text{ V}, f = 1\text{ MHz}$	5.433		6.369	pF
	$C_{D(17V)}$	$V_R = 17\text{ V}, f = 1\text{ MHz}$	2.945		3.452	pF
Capacitance ratio	$C_{D(2V)}/C_{D(25V)}$		5.95		7.26	—
Diode capacitance deviation	ΔC	$C_{D(2V)(10V)(17V)(25V)}$			2	%
Series resistance*	r_D	$C_D = 9\text{ pF}, f = 470\text{ MHz}$			0.6	Ω

Note) 1. Rated input/output frequency: 470 MHz

2. * : r_f measuring instrument: YHP MODEL 4191A RF IMPEDANCE ANALYZER

Note) The part number in the parenthesis shows conventional part number.



Maintenance/Discontinued

Maintenance/Discontinued includes following four Product lifecycle stage.
(planned maintenance type, maintenance type, planned discontinued type, discontinued type)

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